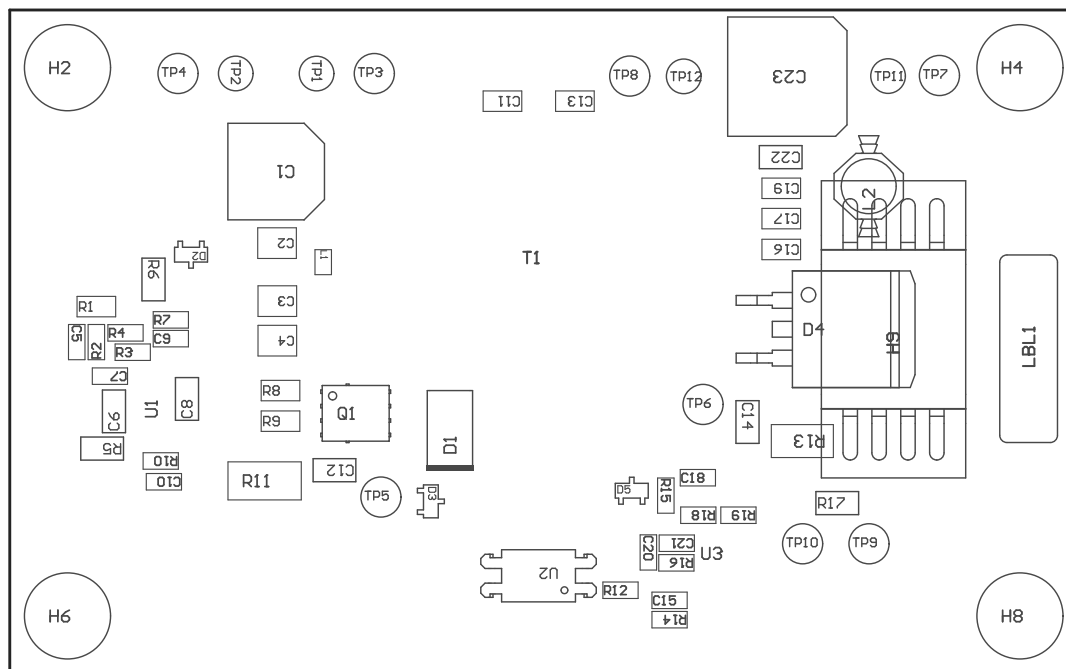


Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP10632	REV: A	SUN REV: Not In VersionControl
IGNORE ->			
PLOT NAME = Top Assembly Drawing	GENERATED : 3/9/2017 2:08:59 PM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP10632	REV: A	SUN REV: Not In VersionControl
	IGNORE ->		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 3/9/2017 2:08:59 PM	TEXAS INSTRUMENTS	

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